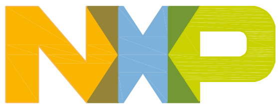

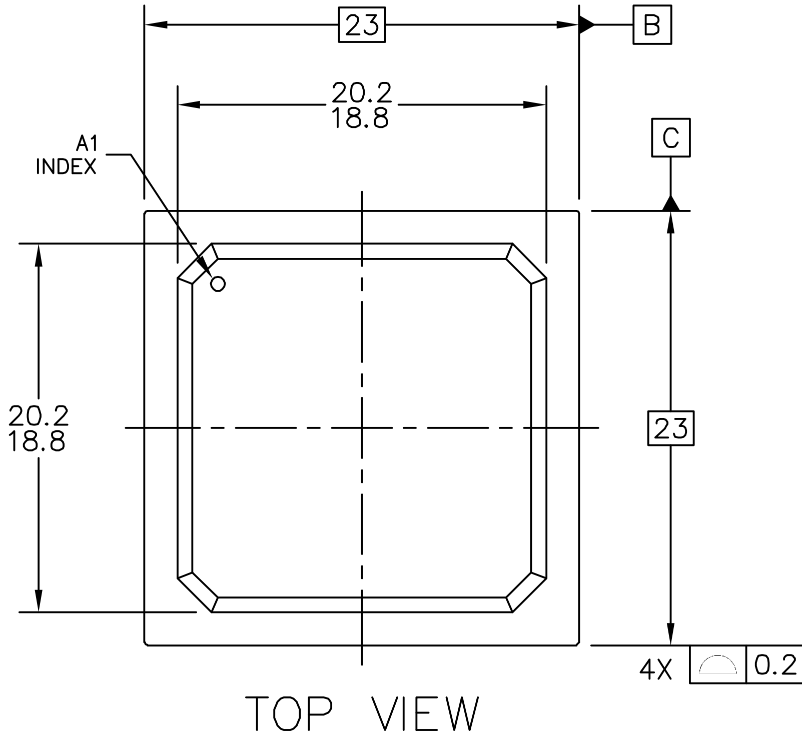

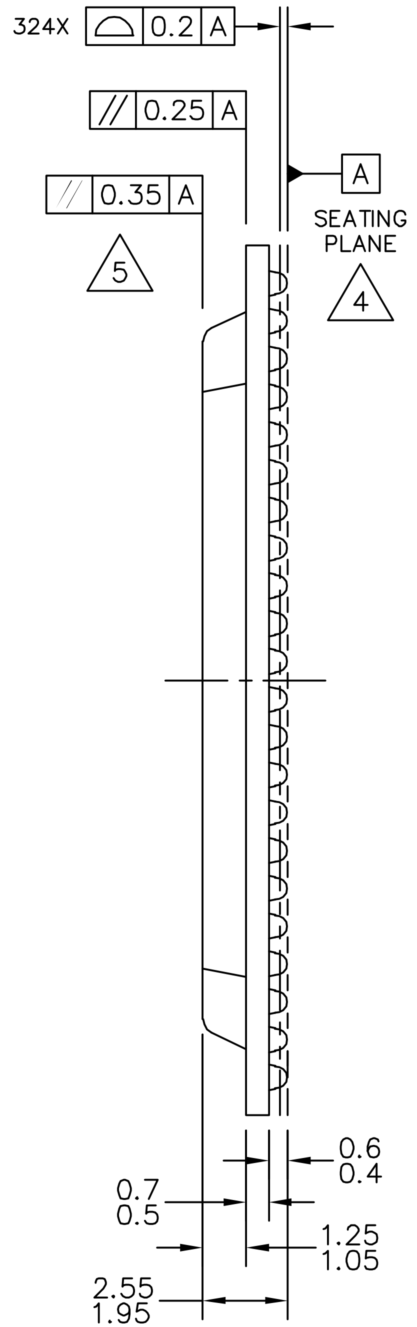

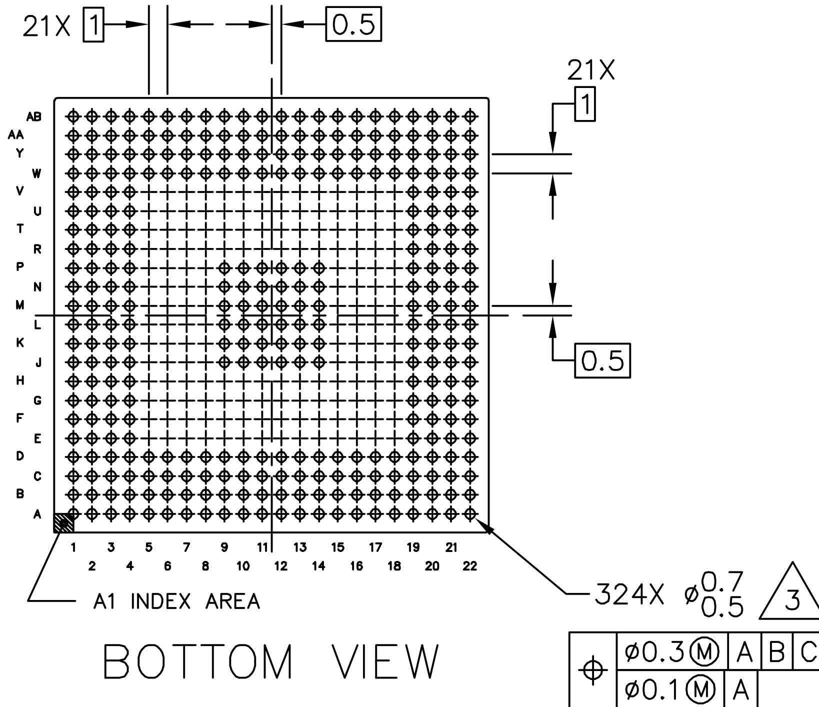

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TITLE: PBGA, 324 I/O, 23 X 23 PKG, 1 MM PITCH (OMPAC)	DOCUMENT NO: 98ASS23840W	REV: F
	STANDARD: JEDEC MS-034 AAJ-1	
	SOT1129-3	27 JAN 2016

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.

2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.

3. (△) MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.

4. (△) DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. (△) PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

6. PACKAGE CODES:
   5241: 2 LAYER 324 PBGA
   5366: 4 LAYER 324 TEPBGA PGE

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